

ABSTRACT

A multilayered polymeric structure having at least two polymeric layers is provided, each layer being a mixture of a polymeric composition with carbon fibrils. The multilayer polymeric structure may include an electrically conductive material between
5 the first and second polymeric layers. A process for making a multilayered polymeric structure for packaging electronic components is also provided. The multilayered polymeric material is used to form trays and packages for containing electrical components.

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